



NO: RD-bel S558-5999-AZ
DATE: 2011/06/02 R (REV:A5)

10/100/1000 BASE-T MAGNETICS MODULES

MODEL NO.: IH-036

FEATURE:

RoHS Compliant

RoHS peak solder rating 260°C/ 3~5 Sec

Do not use material and use that the prohibition that SS-00259 stipulates

Designed to meet IR requirement

Operating temp. : 0°C~80°C

Specifications @ 25°C

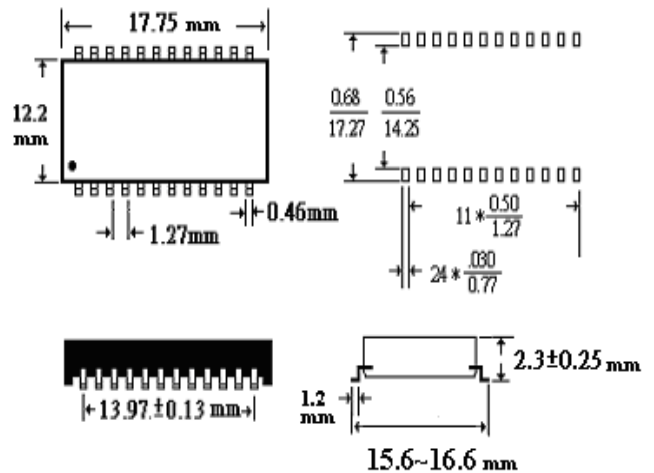
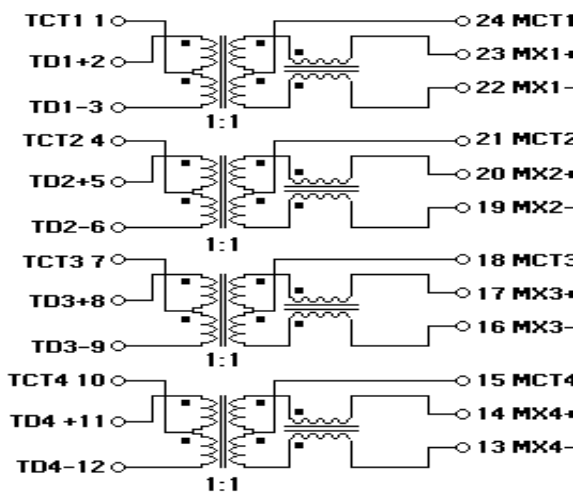
OCL : 350 uH Min @ 8mA (100KHz / 100mV)

MSL=2

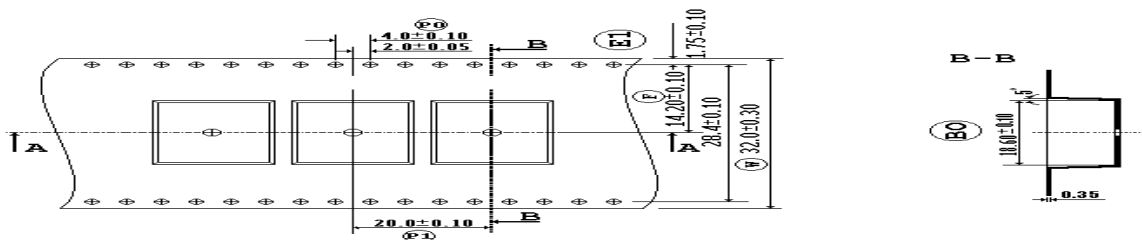
Part Number	Insertion Loss (dB MAX)	Return Loss (dB Min @100Ω)						Differential to Common Mode Rejection (dB MIN)			Cross talk (dB MIN)			Hi pot (Vrms MIN)
		1~100 MHz	1-30	40	50	60-80	100 MHz	30	60	100 MHz	30	60	100 MHz	
IH-036	1.0	-18	-14	-13	-12	-10	-43	-37	-33	-45	-40	-35	1500	

SCHEMATICS:

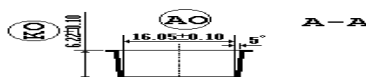
DIMENSION : mm TOLERANCE:±0.25



Packing :



W: 32.0±0.30
P1 : 20.0±0.10
AO : 16.05±0.10
BO : 18.60±0.10
KO : 6.22±0.10
Tape & Reel ----800/reel
Tube-----28/tube



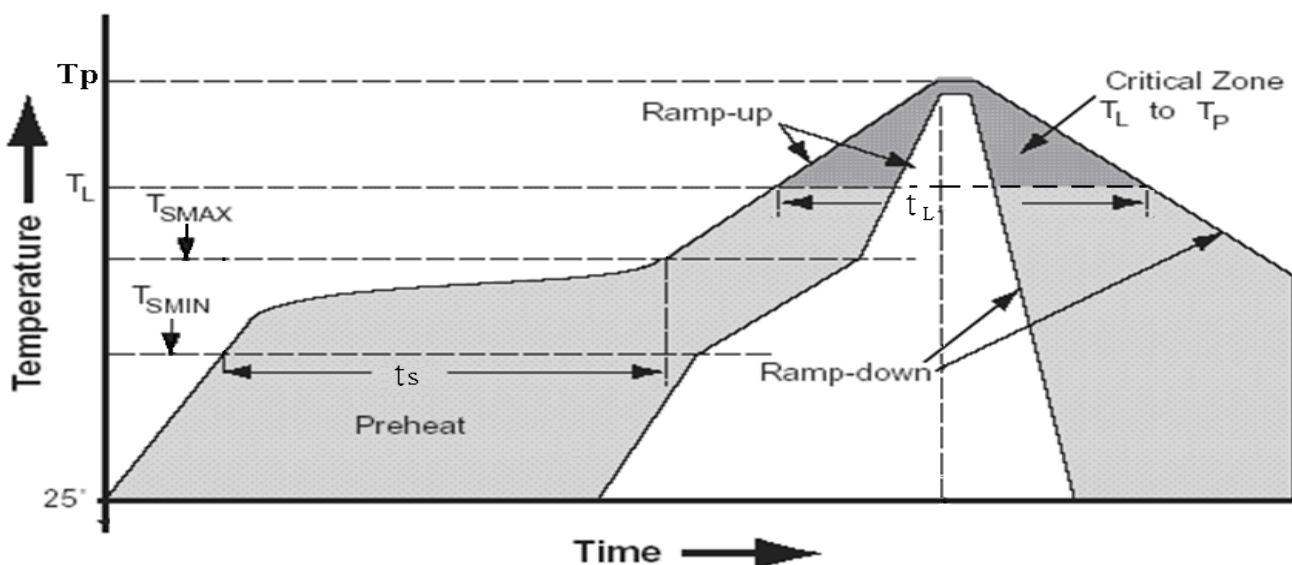
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Solder Reflow profile for Lead-Free packages.
Package Peak Reflow Temperatures

Classification Reflow Profiles

Profile Feature	Lead-Free Assembly	
Average ramp-up rate(T_L to T_P)	3°C / Second Max.	
Preheat		
Temperature Min.(T_s min.)	150 °C	
Temperature Max.(T_s max.)	200 °C	
Time (min to max) (t_s)	60-180 sec	
T_s max. to T_L Ramp-up Rate	3°C / Second Max.	
Time maintained above Temperature (T_L) Time (t_L)	217 °C 60-150 sec	
Peak Tempure (T_p)	260 +0 / -5 °C	250 +0 / -5 °C
Time within 5 °C of actual peak Temp.	3 to 5 Sec	20 to 40 Sec
Ramp-down	6°C / Second Max.	
Time 25 °C to Peak Temperature	8 minutes Max.	

Profile



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PACKING

1. Tape & Reel : 800pcs / Reel , 4000pcs / Carton
2. Dry Pack : 1pcs
Product Description:(5g Silica Gel Desiccant)
PH: 4-8
Package Materials: Paper(Length 6.5±1cm , Width 5±1cm)
3. Reel Packed By Vacuum
4. Seal Per Jedec

